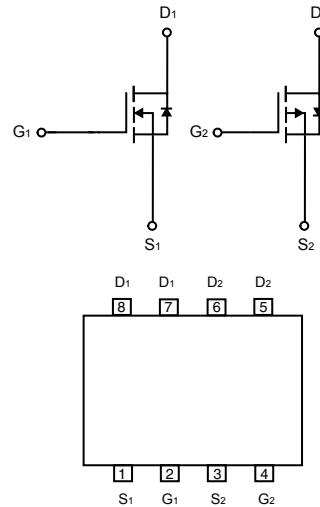
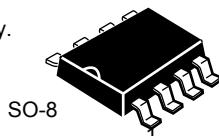


Dual Enhancement Mode Field Effect Transistor (N and P Channel)

FEATURES

- 20V, 7.5A, $R_{DS(ON)} = 22m\Omega$ @ $V_{GS} = 10V$.
 $R_{DS(ON)} = 25m\Omega$ @ $V_{GS} = 4.5V$.
 $R_{DS(ON)} = 40m\Omega$ @ $V_{GS} = 2.5V$.
- -20V, -4A, $R_{DS(ON)} = 80m\Omega$ @ $V_{GS} = -10V$.
 $R_{DS(ON)} = 100m\Omega$ @ $V_{GS} = -4.5V$.
 $R_{DS(ON)} = 150m\Omega$ @ $V_{GS} = -2.5V$.
- Super high dense cell design for extremely low $R_{DS(ON)}$.
- High power and current handing capability.
- Lead free product is acquired.
- Surface mount Package.

ABSOLUTE MAXIMUM RATINGS $T_A = 25^\circ C$ unless otherwise noted

| Parameter | Symbol | N-Channel | P-Channel | Units |
|---------------------------------------|----------------|------------|-----------|-------|
| Drain-Source Voltage | V_{DS} | 20 | -20 | V |
| Gate-Source Voltage | V_{GS} | ± 12 | ± 12 | V |
| Drain Current-Continuous | I_D | 7.5 | -4.0 | A |
| Drain Current-Pulsed ^a | I_{DM} | 30 | -16 | A |
| Maximum Power Dissipation | P_D | 2.0 | | W |
| Operating and Store Temperature Range | T_J, T_{stg} | -55 to 150 | | °C |

Thermal Characteristics

| Parameter | Symbol | Limit | Units |
|--|-----------------|-------|-------|
| Thermal Resistance, Junction-to-Ambient ^b | $R_{\theta JA}$ | 62.5 | °C/W |



CEM2539A

N-Channel Electrical Characteristics $T_A = 25\text{ C}$ unless otherwise noted

| Parameter | Symbol | Test Condition | Min | Typ | Max | Units |
|---|---------------------|---|-----|-----|------|------------------|
| Off Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | BV_{DSS} | $V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$ | 20 | | | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS} = 20\text{V}, V_{GS} = 0\text{V}$ | | | 1 | μA |
| Gate Body Leakage Current, Forward | I_{GSSF} | $V_{GS} = 12\text{V}, V_{DS} = 0\text{V}$ | | | 100 | nA |
| Gate Body Leakage Current, Reverse | I_{GSSR} | $V_{GS} = -12\text{V}, V_{DS} = 0\text{V}$ | | | -100 | nA |
| On Characteristics^c | | | | | | |
| Gate Threshold Voltage | $V_{GS(\text{th})}$ | $V_{GS} = V_{DS}, I_D = 250\mu\text{A}$ | 0.6 | | 2 | V |
| Static Drain-Source On-Resistance | $R_{DS(\text{on})}$ | $V_{GS} = 10\text{V}, I_D = 7.3\text{A}$ | | 18 | 22 | $\text{m}\Omega$ |
| | | $V_{GS} = 4.5\text{V}, I_D = 6.4\text{A}$ | | 20 | 25 | $\text{m}\Omega$ |
| | | $V_{GS} = 2.5\text{V}, I_D = 4.5\text{A}$ | | 26 | 40 | $\text{m}\Omega$ |
| Dynamic Characteristics^d | | | | | | |
| Input Capacitance | C_{iss} | $V_{DS} = 8\text{V}, V_{GS} = 0\text{V}, f = 1.0 \text{ MHz}$ | | 910 | | pF |
| Output Capacitance | C_{oss} | | | 230 | | pF |
| Reverse Transfer Capacitance | C_{rss} | | | 165 | | pF |
| Switching Characteristics^d | | | | | | |
| Turn-On Delay Time | $t_{d(on)}$ | $V_{DD} = 10\text{V}, I_D = 1\text{A}, V_{GS} = 4.5\text{V}, R_{GEN} = 6\Omega$ | | 13 | 26 | ns |
| Turn-On Rise Time | t_r | | | 9.5 | 19 | ns |
| Turn-Off Delay Time | $t_{d(off)}$ | | | 34 | 68 | ns |
| Turn-Off Fall Time | t_f | | | 10 | 20 | ns |
| Total Gate Charge | Q_g | $V_{DS} = 10\text{V}, I_D = 6\text{A}, V_{GS} = 4.5\text{V}$ | | 10 | 13 | nC |
| Gate-Source Charge | Q_{gs} | | | 1.4 | | nC |
| Gate-Drain Charge | Q_{gd} | | | 3.1 | | nC |
| Drain-Source Diode Characteristics and Maximum Ratings | | | | | | |
| Drain-Source Diode Forward Current ^b | I_S | | | | 7.5 | A |
| Drain-Source Diode Forward Voltage ^c | V_{SD} | $V_{GS} = 0\text{V}, I_S = 1\text{A}$ | | | 1 | V |

Notes :

- a.Repetitive Rating : Pulse width limited by maximum junction temperature.□
- b.Surface Mounted on FR4 Board, $t < 5 \text{ sec.}$ □
- c.Pulse Test : Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.□
- d.Guaranteed by design, not subject to production testing.□



CEM2539A

P-Channel Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise noted

| Parameter | Symbol | Test Condition | Min | Typ | Max | Units |
|---|----------------------------|---|------|------|------|------------------|
| Off Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | BV_{DSS} | $V_{\text{GS}} = 0\text{V}, I_D = -250\mu\text{A}$ | -20 | | | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{\text{DS}} = -20\text{V}, V_{\text{GS}} = 0\text{V}$ | | | -1 | μA |
| Gate Body Leakage Current, Forward | I_{GSSF} | $V_{\text{GS}} = 12\text{V}, V_{\text{DS}} = 0\text{V}$ | | | 100 | nA |
| Gate Body Leakage Current, Reverse | I_{GSSR} | $V_{\text{GS}} = -12\text{V}, V_{\text{DS}} = 0\text{V}$ | | | -100 | nA |
| On Characteristics^c | | | | | | |
| Gate Threshold Voltage | $V_{\text{GS}(\text{th})}$ | $V_{\text{GS}} = V_{\text{DS}}, I_D = -250\mu\text{A}$ | -0.5 | | -1 | V |
| Static Drain-Source On-Resistance | $R_{\text{DS}(\text{on})}$ | $V_{\text{GS}} = -10\text{V}, I_D = -3.5\text{A}$ | | 70 | 80 | $\text{m}\Omega$ |
| | | $V_{\text{GS}} = -4.5\text{V}, I_D = -2.8\text{A}$ | | 80 | 100 | $\text{m}\Omega$ |
| | | $V_{\text{GS}} = -2.5\text{V}, I_D = -2.0\text{A}$ | | 90 | 150 | $\text{m}\Omega$ |
| Dynamic Characteristics^d | | | | | | |
| Forward Transconductance | g_{FS} | $V_{\text{DS}} = -5\text{V}, I_D = -3.5\text{A}$ | | 10 | | S |
| Input Capacitance | C_{iss} | $V_{\text{DS}} = -10\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$ | | 1180 | | pF |
| Output Capacitance | C_{oss} | | | 235 | | pF |
| Reverse Transfer Capacitance | C_{rss} | | | 125 | | pF |
| Switching Characteristics^d | | | | | | |
| Turn-On Delay Time | $t_{\text{d}(\text{on})}$ | $V_{\text{DD}} = -10\text{V}, I_D = -4\text{A}, V_{\text{GS}} = -4.5\text{V}, R_{\text{GEN}} = 3\Omega$ | | 14.6 | 29.2 | ns |
| Turn-On Rise Time | t_r | | | 9.2 | 18.4 | ns |
| Turn-Off Delay Time | $t_{\text{d}(\text{off})}$ | | | 73 | 146 | ns |
| Turn-Off Fall Time | t_f | | | 36 | 72 | ns |
| Total Gate Charge | Q_g | $V_{\text{DS}} = -10\text{V}, I_D = -3.7\text{A}, V_{\text{GS}} = -4.5\text{V}$ | | 10.8 | 14.3 | nC |
| Gate-Source Charge | Q_{gs} | | | 1.7 | | nC |
| Gate-Drain Charge | Q_{gd} | | | 2.7 | | nC |
| Drain-Source Diode Characteristics and Maximum Ratings | | | | | | |
| Drain-Source Diode Forward Current ^b | I_s | | | | -3.7 | A |
| Drain-Source Diode Forward Voltage ^c | V_{SD} | $V_{\text{GS}} = 0\text{V}, I_s = -1\text{A}$ | | | -1 | V |

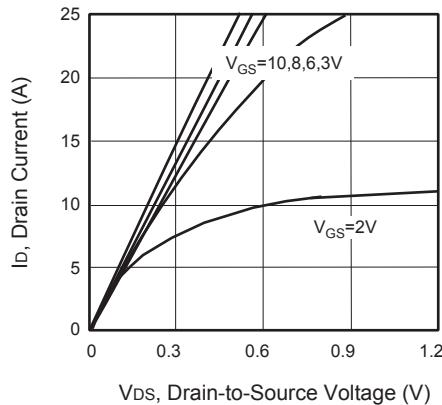
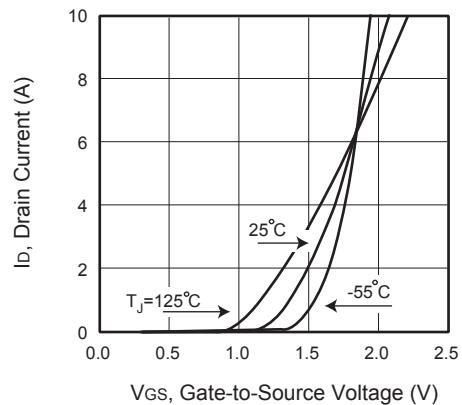
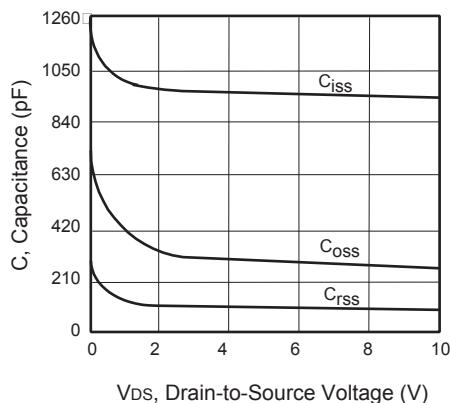
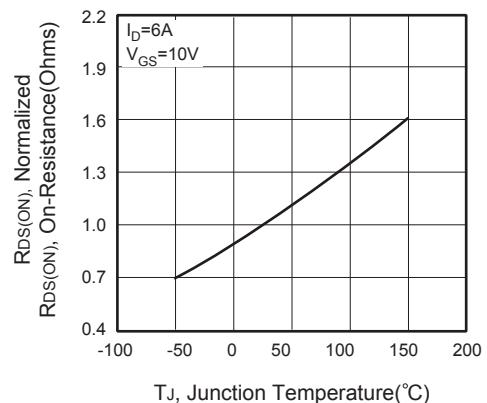
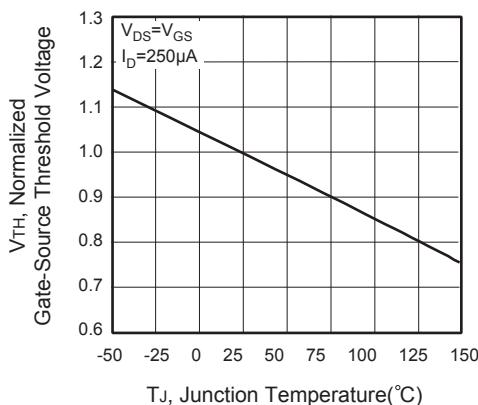
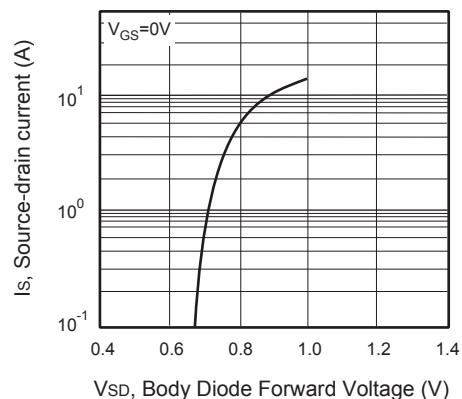
Notes :

a.Repetitive Rating : Pulse width limited by maximum junction temperature.□

b.Surface Mounted on FR4 Board, t ≤ 10 sec.□

c.Pulse Test : Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.□

d.Guaranteed by design, not subject to production testing.□

N-CHANNEL**Figure 1. Output Characteristics****Figure 2. Transfer Characteristics****Figure 3. Capacitance****Figure 4. On-Resistance Variation with Temperature****Figure 5. Gate Threshold Variation with Temperature****Figure 6. Body Diode Forward Voltage Variation with Source Current**

P-CHANNEL

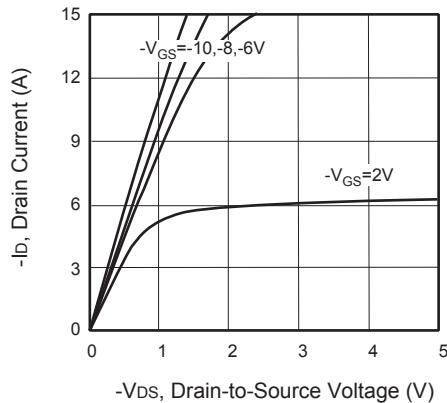


Figure 7. Output Characteristics

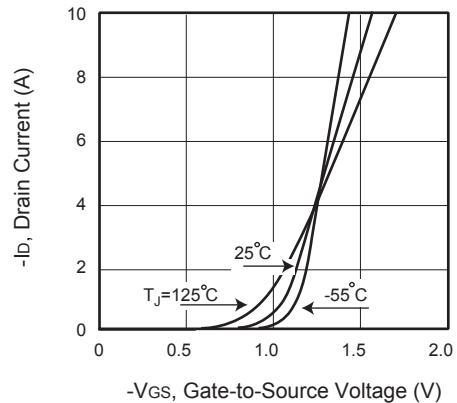


Figure 8. Transfer Characteristics

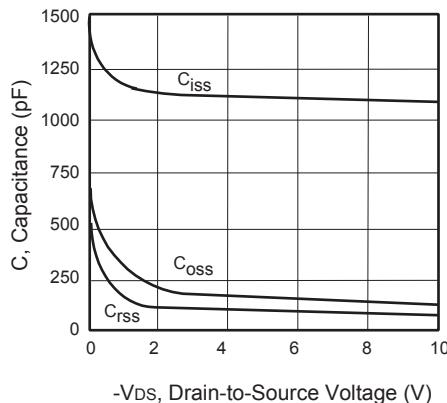


Figure 9. Capacitance

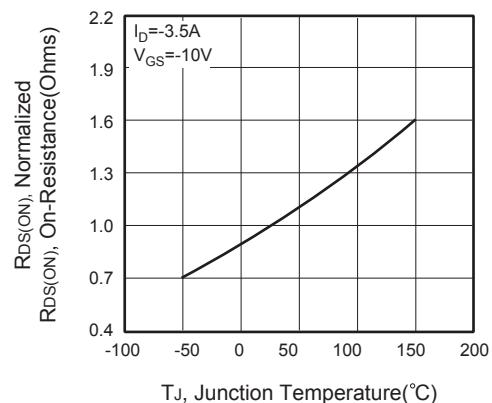


Figure 10. On-Resistance Variation with Temperature

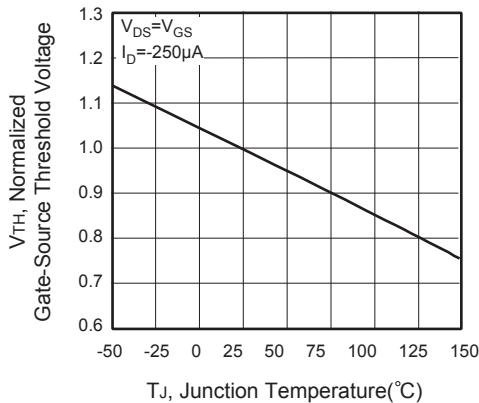


Figure 11. Gate Threshold Variation with Temperature

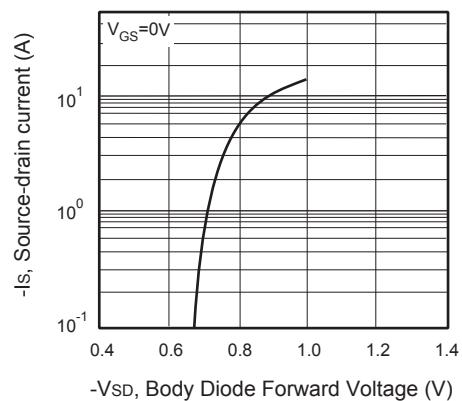
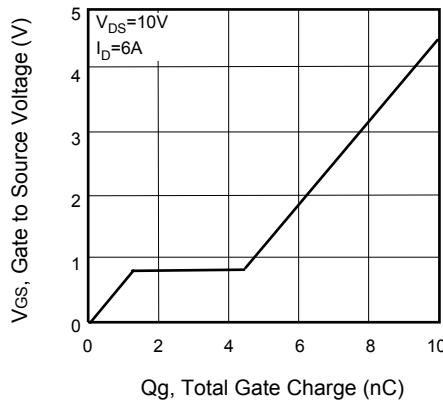
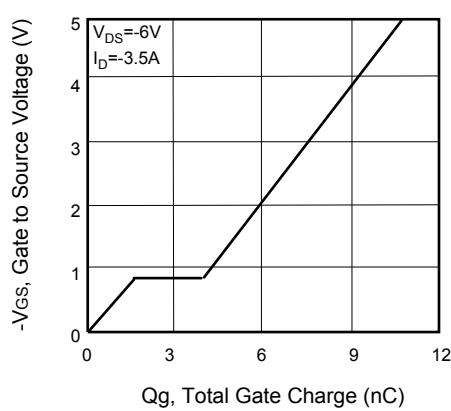
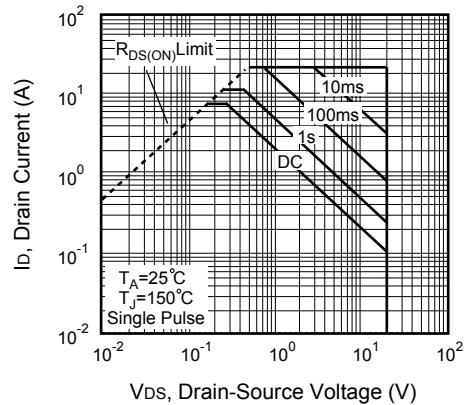
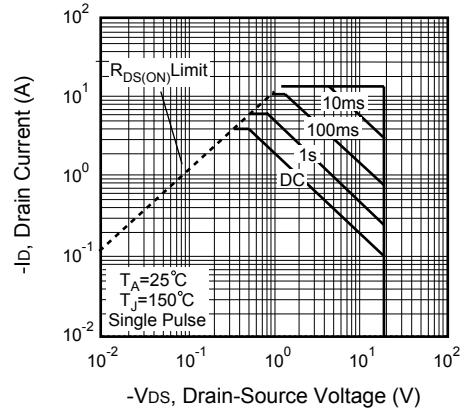


Figure 12. Body Diode Forward Voltage Variation with Source Current

N-CHANNEL**Figure 13. Gate Charge****P-CHANNEL****Figure 15. Gate Charge****Figure 14. Maximum Safe Operating Area****Figure 16. Maximum Safe Operating Area**

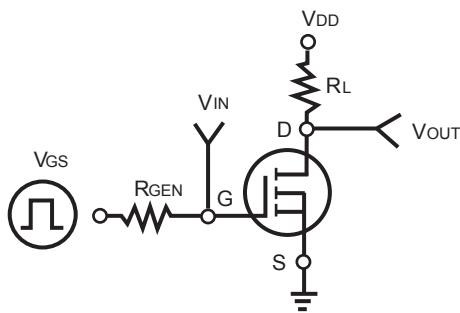


Figure 17. Switching Test Circuit

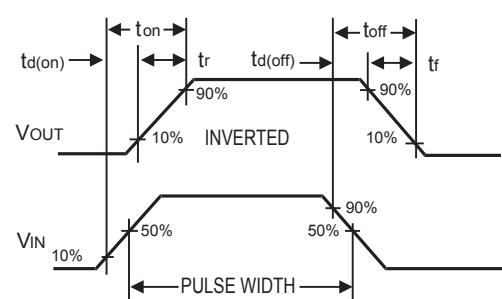


Figure 18. Switching Waveforms

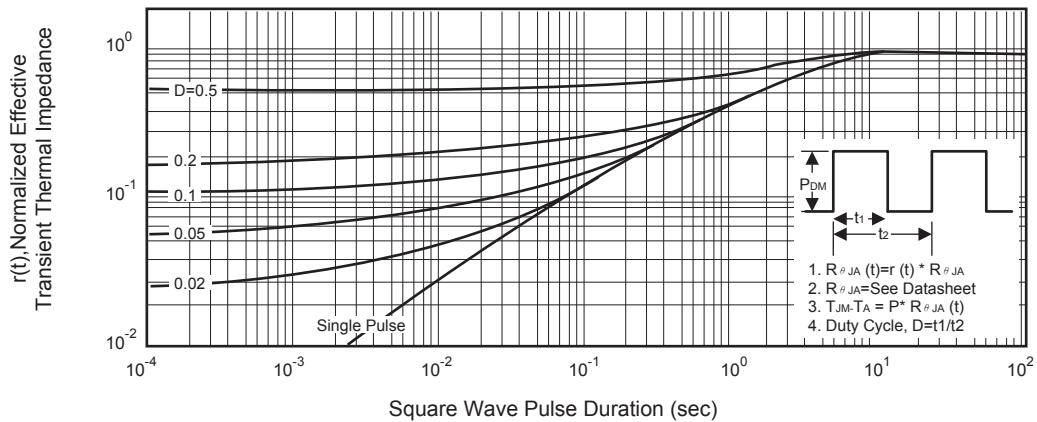


Figure 19. Normalized Thermal Transient Impedance Curve